Authorized Representative* Title - Representative Phone - Representative* Email - Representative*	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-21 Contact Name Product Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onse Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* Unique ID Authority Response Date* 2024-05-21 Response Date	ials and Mfg Information						
2024-05-21 202							
Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM NTMFS4899NFT1G NFET SO8FL 30V 75A 5MO 2024-05-21 MY1 100.77 mg	Response Date*						
Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product-Env-Steward	2024-05-21						
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Pffective Date NY MY1 MY1 MY1 MY1 MY1 MY1 MY1 MY1 MY1 MY	Email - Contact*						
Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onset	Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM NTMFS4899NFT1G NFET SO8FL 30V 75A 5MO 2024-05-21 MY1 100.77 mg	Email - Representative*						
NTMFS4899NFT1G NFET SO8FL 30V 75A 5MO 2024-05-21 MY1 100.77 mg	Product-Env-Stewards@onsemi.com						
	M Unit Type						
Ianufacturing Proccess Information	Each						
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflo	low Cycles						
Matte Tin (Sn) - annealed CU Alloy 1 CU A	low Cycles						
omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds							
or more information regarding material composition please refer to page 3							

RoHS Material Composition Declaration			Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is trouch in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicab									
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature Ra	astislav Drska	-En							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach Solder	2.33	mg	Supplier	Silver (Ag)	7440-22-4		0.0582	mg
			A	Lead (Pb)	7439-92-1	7a	2.1553	mg
			Supplier	Tin (Sn)	7440-31-5		0.1165	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0048	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0952	mg
			Supplier	Iron (Fe)	7439-89-6		1.2371	mg
			Supplier	Copper (Cu)	7440-50-8		46.1915	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0714	mg
Mold Compound-Black	42.24 mg	42.24 mg		Epoxy resin	proprietary data		3.168	mg
			Supplier	Phenolic Resin	Proprietary Data		1.056	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.168	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.6368	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg